

High-Reliability Alloy

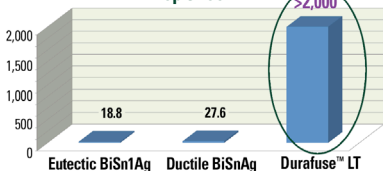
Durafuse™ LT*

Innovative Low-Temperature Alloy Technology

Durafuse™ LT is a novel mixed-powder approach that solves the challenges of brittle bismuth-based low-temperature solder joints at a reasonable price point compared to indium-based and SAC solders.

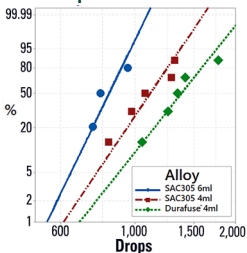
Improves Drop Shock Resistance

Drop Shock



44g ball at 500mm drop height.

Drop Shock vs. SAC305



Weibull plot of 100g ball with 500mm drop height.

*Patented

Contact our engineers: askus@indium.com

Learn more: www.indium.com

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

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Form No. 99725 R4

High-Performance Reliability

- Drop shock resilience
 - Outclasses BiSn or BiSnAg alloys
 - Performance equal to or better than SAC305
- Peak reflow below 210°C
- High re-melt temperature

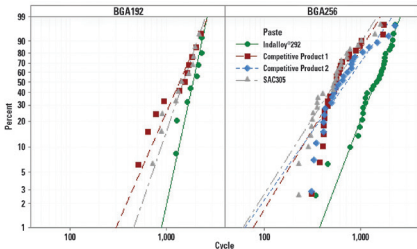


High-Reliability Alloy Indalloy[®] 292

Indalloy[®] 292 provides exceptional thermal cycling performance (-40/+150°C).

Superior BGA Lifetime Reliability

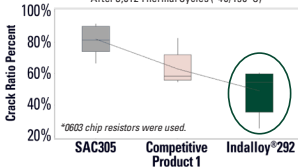
-40/+150°C Thermal Cycle Testing on OSP Weibull Plot



Indalloy[®] 292 demonstrates superior TCT performance over competing high-reliability alloys.

Solder Joint Crack Comparison*

After 3,012 Thermal Cycles (-40/150°C)



DEFECT:
Cracking

SOLUTION:
Indalloy[®] 292

Excellent thermal cycling performance (-40/150°C). High shear strength and low solder joint cracking. Pinhole elimination improves joint appearance.

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